

2SK2929

Silicon N Channel MOS FET High Speed Power Switching

REJ03G1043-0500

(Previous: ADE-208-552C)

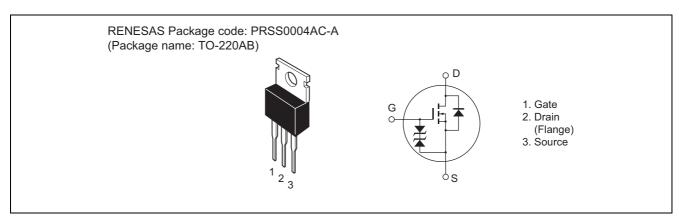
Rev.5.00

Sep 07, 2005

Features

- Low on-resistance $R_{DS} = 0.026 \Omega$ typ.
- High speed switching
- 4 V gate drive device can be driven from 5 V source

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	60	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	I _D	25	А
Drain peak current	I _{D(pulse)} Note1	100	А
Body-drain diode reverse drain current	I _{DR}	25	А
Avalanche current	I _{AP} Note3	20	A
Avalanche energy	E _{AR} Note3	34	mJ
Channel dissipation	Pch Note2	50	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	−55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Tc = 25°C

3. Value at Tch = 25°C, Rg \geq 50 Ω

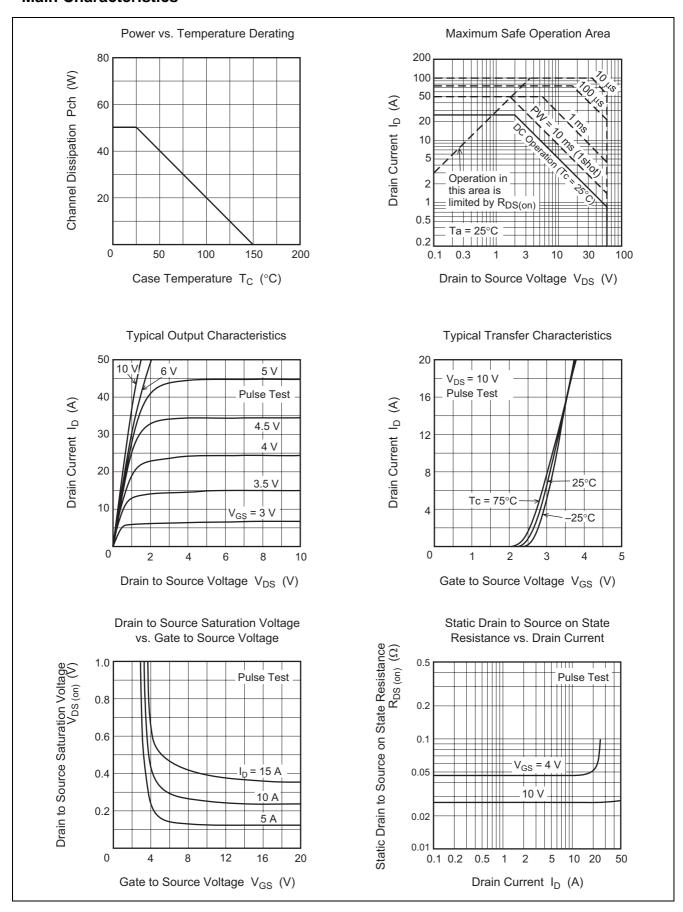
Electrical Characteristics

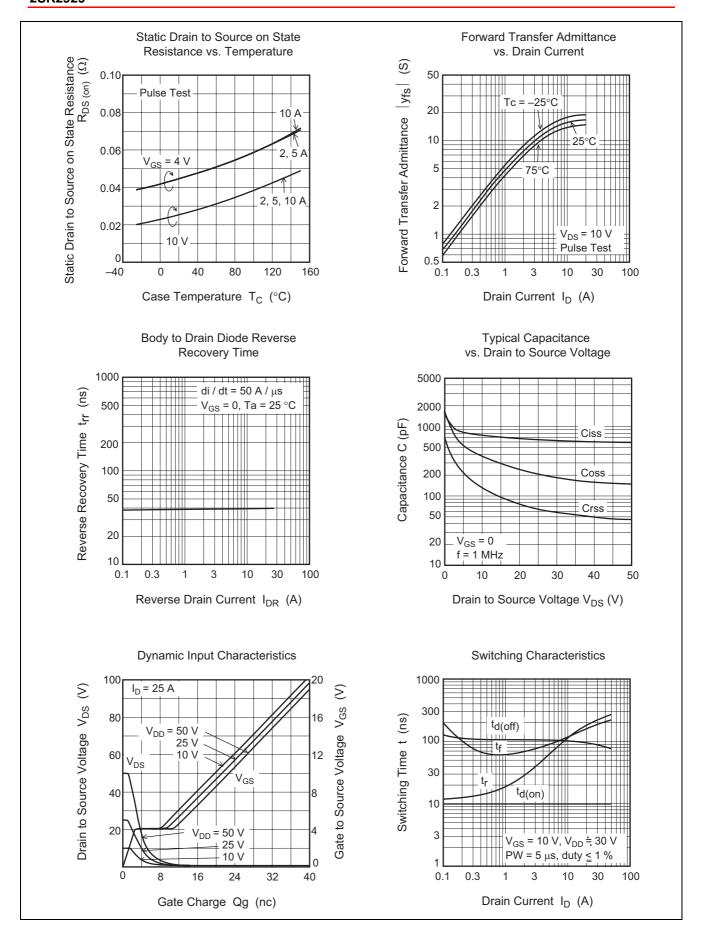
 $(Ta = 25^{\circ}C)$

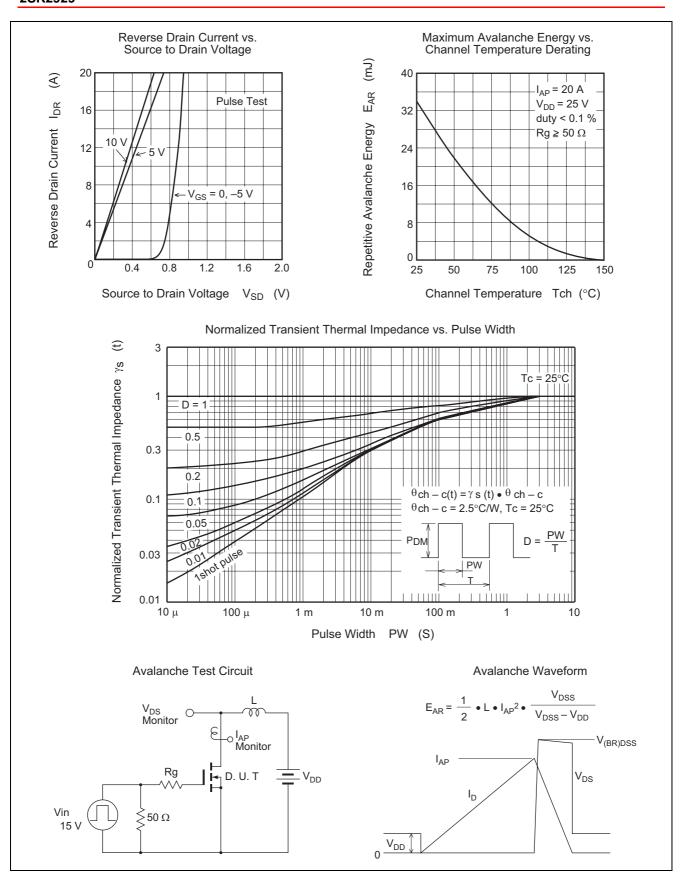
Item	Symbol	Min	Тур	Max	Unit	Test Conditions	
Drain to source breakdown voltage	$V_{(BR)DSS}$	60	_	_	V	$I_D = 10 \text{m A}, V_{GS} = 0$	
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$	
Gate to source leak current	I_{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$	
Zero gate voltage drain current	I _{DSS}		_	10	μΑ	$V_{DS} = 60 \text{ V}, V_{GS} = 0$	
Gate to source cutoff voltage	$V_{GS(off)}$	1.5	_	2.5	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$	
Static drain to source on state	R _{DS(on)}	_	0.026	0.034	Ω	$I_D = 15 \text{ A}, V_{GS} = 10 \text{ V}^{Note4}$	
resistance	R _{DS(on)}	_	0.045	0.07	Ω	$I_D = 15 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note4}}$	
Forward transfer admittance	y _{fs}	11	17	_	S	$I_D = 15 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$	
Input capacitance	Ciss	_	740	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$	
Output capacitance	Coss	_	380	_	pF	f = 1 MHz	
Reverse transfer capacitance	Crss	_	140	_	pF	1	
Turn-on delay time	t _{d(on)}	_	10	_	ns	$I_D = 15 \text{ A}, V_{GS} = 10 \text{ V},$	
Rise time	t _r	_	160	_	ns	$R_L = 2 \Omega$	
Turn-off delay time	t _{d(off)}	_	100	_	ns		
Fall time	t _f	_	150	_	ns		
Body-drain diode forward voltage	V_{DF}	_	0.95	_	V	$I_F = 25 \text{ A}, V_{GS} = 0$	
Body-drain diode reverse recovery time	t _{rr}	_	40	_	ns	$I_F = 25 \text{ A}, V_{GS} = 0$ $di_{F}/dt = 50 \text{ A}/\mu\text{s}$	

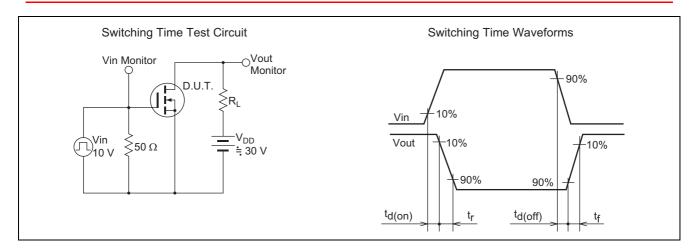
Note: 4. Pulse test

Main Characteristics

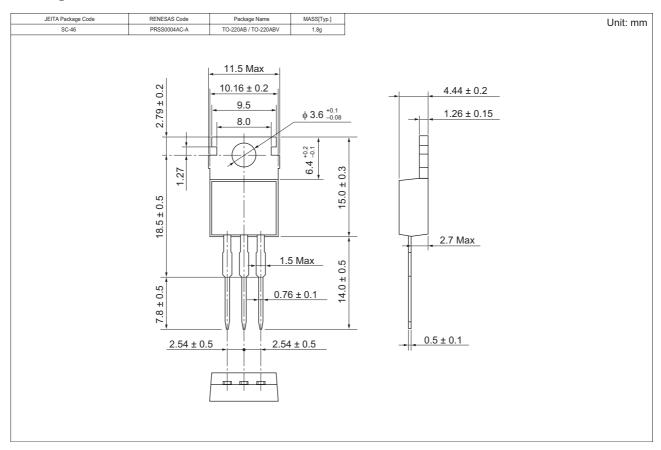








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK2929-e	500 pcs	Box (Sack)

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